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(54) **Title:** COMPOSITION FOR CLEANING SUBSTRATES POST-CHEMICAL MECHANICAL POLISHING

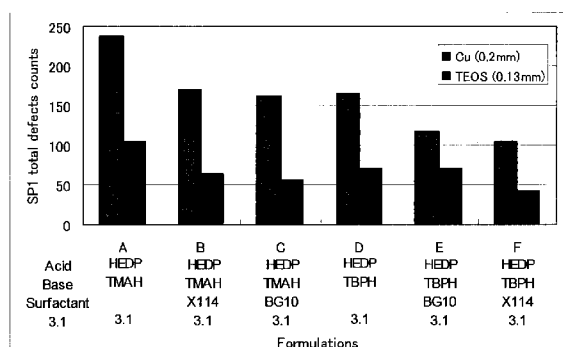


Fig. 1

(57) **Abstract:** A semiconductor processing composition and method for cleaning semiconductor wafers post chemical mechanical polishing comprising a phosphorous base and optionally at least one surfactant.